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(54) **Method of manufacturing an external force detection sensor**

(57) A method of manufacturing an external force detection sensor in which a sensor element is formed by

through-hole (20) dry etching of an element substrate (3), and an electrically conductive material is used as an etching stop layer (18) during the dry etching.

FIG. 1A

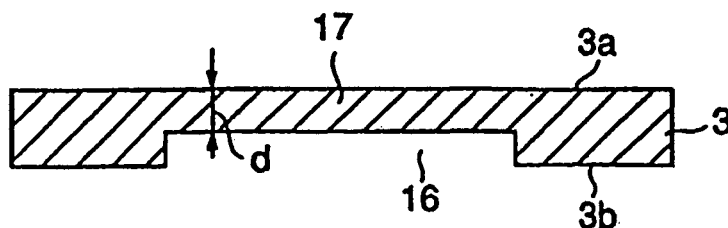


FIG. 1B

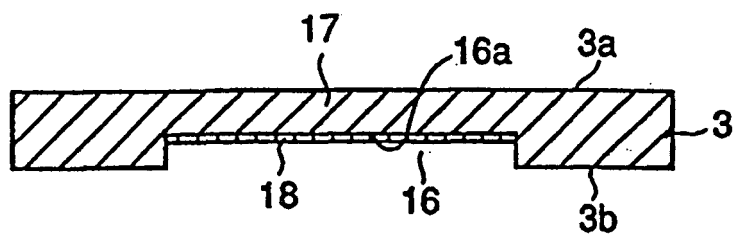


FIG. 1C

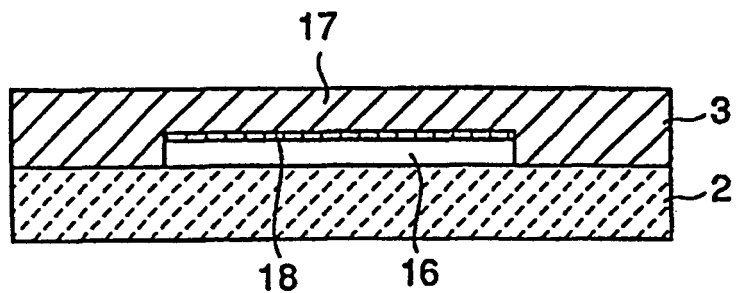


FIG. 1D

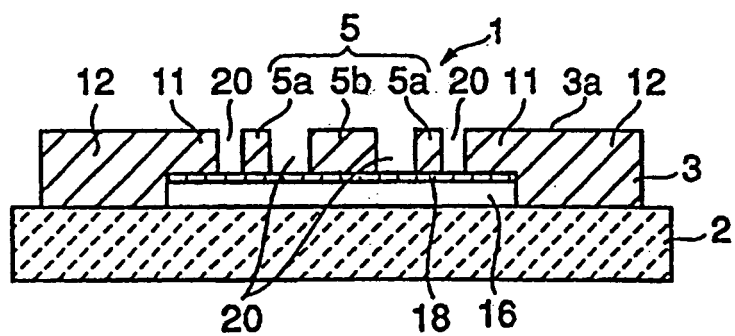
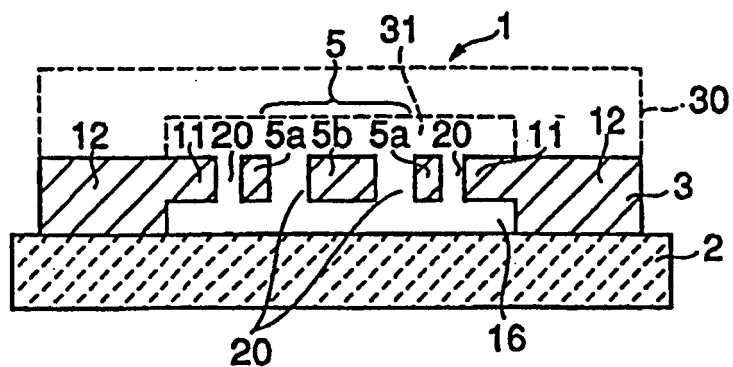


FIG. 1E





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Category	Citation of document with indication, where appropriate, of relevant passages	Relevant to claim	CLASSIFICATION OF THE APPLICATION (IPC)
X	US 5 610 431 A (MARTIN JACOB H) 11 March 1997 (1997-03-11) * column 5, line 5 - line 40; figures 1-5 *	1	INV. G01P15/08
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The present search report has been drawn up for all claims			
Place of search Munich		Date of completion of the search 6 November 2007	Examiner Götz, Andreas
CATEGORY OF CITED DOCUMENTS X : particularly relevant if taken alone Y : particularly relevant if combined with another document of the same category A : technological background O : non-written disclosure P : intermediate document T : theory or principle underlying the invention E : earlier patent document, but published on, or after the filing date D : document cited in the application L : document cited for other reasons & : member of the same patent family, corresponding document			

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**ANNEX TO THE EUROPEAN SEARCH REPORT
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